

TI-27698

JMC

⑥ Assembly member into package

Use standard K6D/IE essay  
 practices using the flip configuration  
 of the K6D/IE configuration

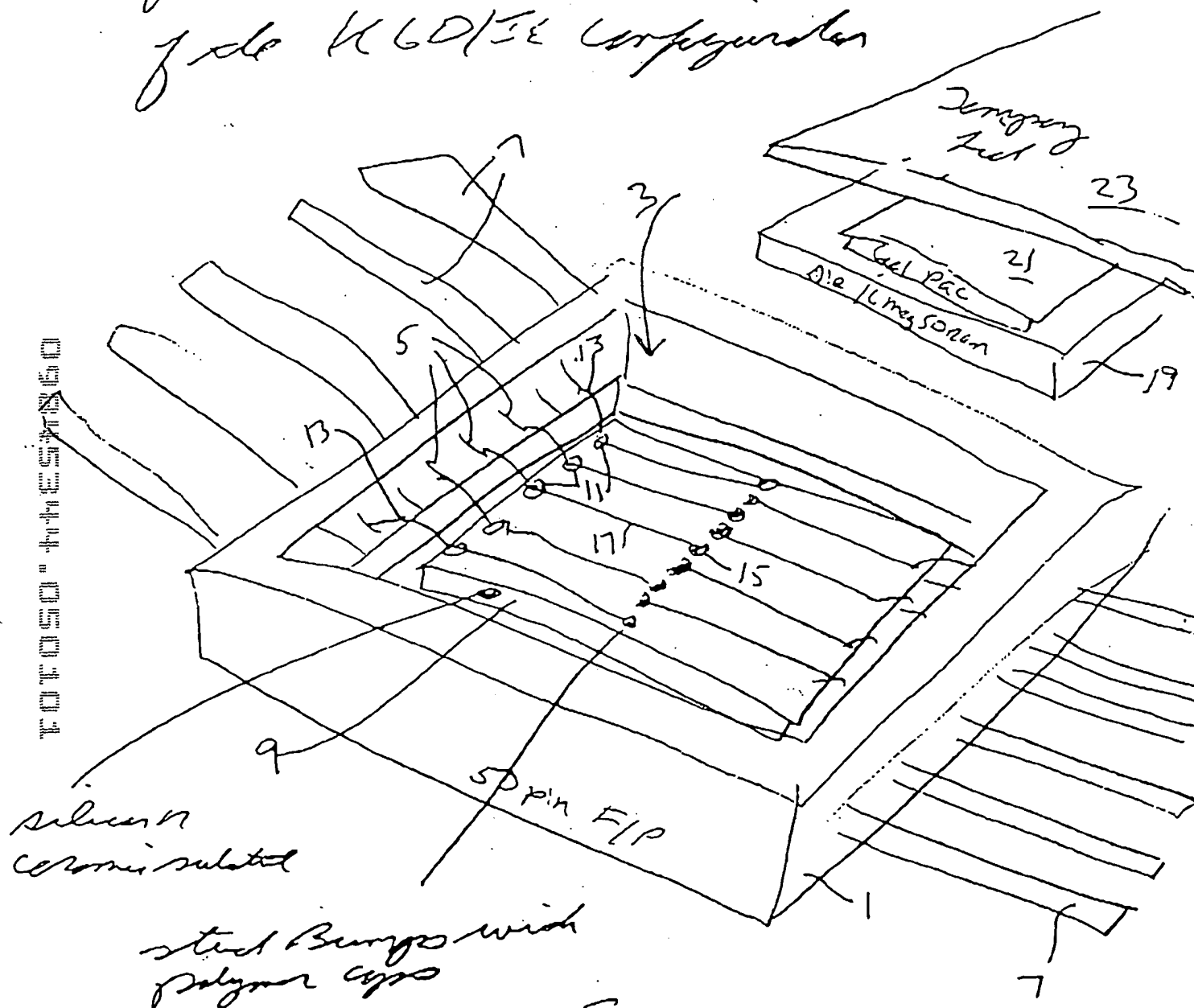


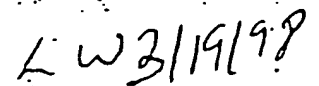
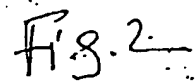
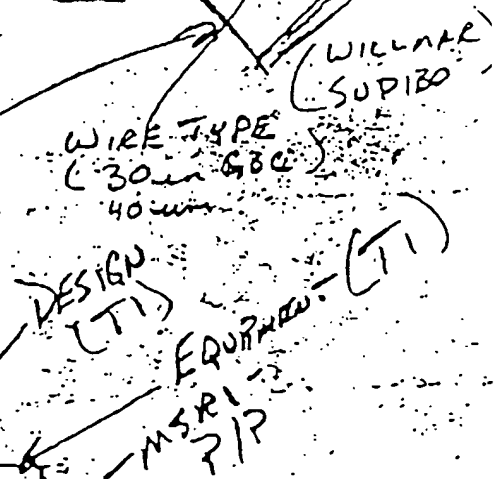
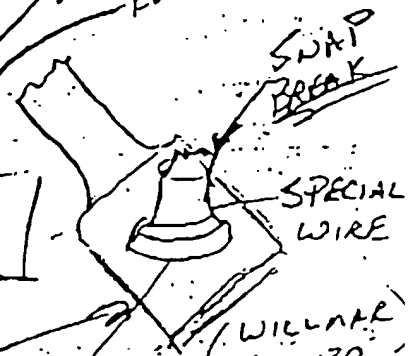
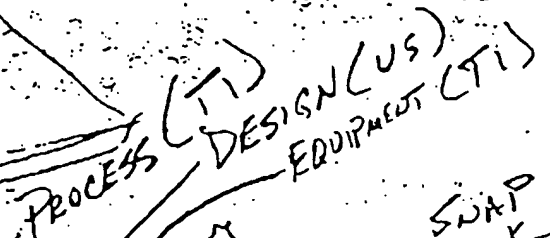
Fig. 1

Assembly member into the correct  
 steel bumps with conductive polymer

RUG 3/19/98

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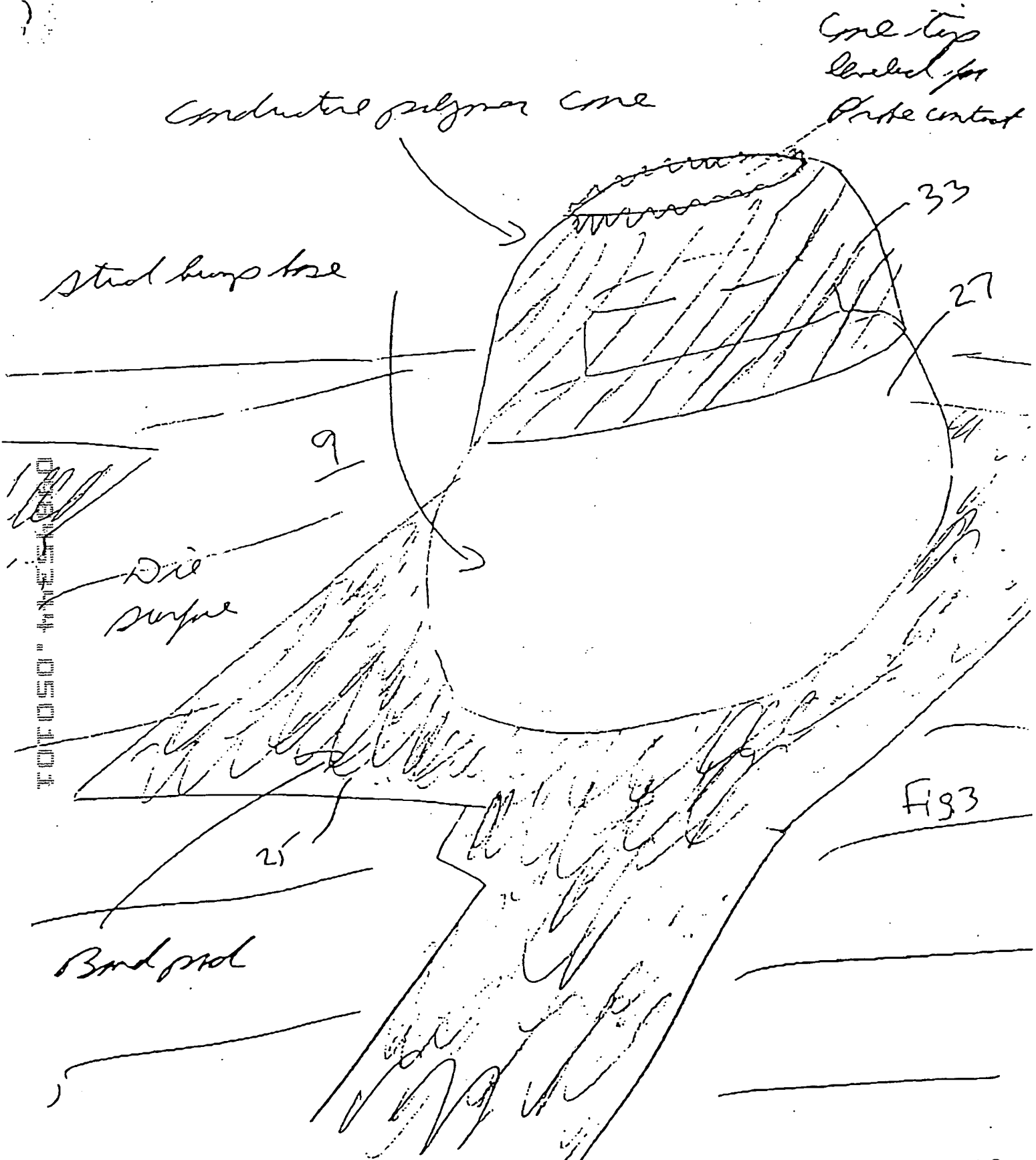
PROCESS [ CERAMIC  
VENDOR ]  
EQUIPMENT [ CERAMIC  
VENDOR ]



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*Stud. cone. bump*

TI-27648  
3



*Final Product for SKB*

*RAW 3/19/97*

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